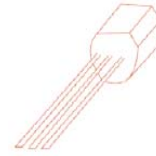


MATERIAL ANALYSIS DATA SHEET



Product Description: BC557 (TO-92)

Material	Supplier	Type	Composition	CAS No.	% of weight	Weight(mg)
Wafer	XinShun	Si	Silicon	7440-21-3	100.00%	0.083
Lead Frame	KangQiang (NingBo)	TFe0.1	Iron	7439-89-6	0.15%	86.660
			Phosphorus	7723-14-0	0.04%	
			Copper	7440-50-8	99.80%	
			Silver	7440-22-4	0.01%	
Wire	Heraeus	Cu	Copper	7440-50-8	100.00%	0.011
Mold Compound	ZhongPeng	SP-100A-2 (1.8)	Silica Quartz	14808-60-7	50.00%	107.147
			Silica Fused	60676-86-0	20.00%	
			Epoxy Resin	Trade Secret	15.00%	
			Phenol Resin	Trade Secret	10.00%	
			Antimony Trioxide	1309-64-4	2.00%	
			Carbon Black	1333-86-4	1.00%	
Brominated Resin	40039-93-8	2.00%				
Plating	yunxi	Sn	Tin	7440-31-5	100.00%	1.342

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